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Total Number of Pages : 02

B.Tech  
REC5D006

5<sup>th</sup>/7<sup>th</sup> Semester Reg/Back Examination: 2025-26

SUBJECT: Digital VLSI Design

BRANCH(S): AEIE, CSE, ECE, EEE, ELECTRICAL, ETC, IT, MECH

Time : 3 Hour

Max Marks : 100

Q. Code : U413

**Answer Question No.1 (Part-I) which is compulsory, any eight from Part-II and any two from Part-III.**

**The figures in the right hand margin indicate marks.**

**Part-I**

**Q1 Answer the following questions: (2 x 10)**

- a) What is CMOS n-well process?
- b) What is meant by dynamic logic?
- c) If the mobility of NMOS is  $450 \text{ cm}^2/\text{V-s}$ , gate width  $10 \mu\text{m}$ , length  $2 \mu\text{m}$ ,  $C_{ox} = 4 \text{ fF}/\mu\text{m}^2$ , and  $V_{GS} = 3\text{V}$ ,  $V_{th} = 0.8\text{V}$ , compute  $I_d$  (saturation).
- d) Write and explain the expression for dynamic power consumption.
- e) What is bootstrapping in MOS circuits?
- f) What is IDDQ testing?
- g) For CMOS inverter with supply  $V_{DD} = 5\text{V}$  and switching threshold  $V_m = 2.5\text{V}$ , find noise margin (NMH, NML).
- h) A DRAM cell stores charge  $Q = 45 \text{ fC}$  at  $V = 1\text{V}$ . Compute storage capacitance.
- i) CMOS inverter switching energy is  $1.6 \text{ pJ}$  per transition. Compute power at  $f = 200 \text{ MHz}$ .
- j) Define MOSFET scaling.

**Part-II**

**Q2 Only Focused-Short Answer Type Questions- (Answer Any Eight out of Twelve) (6 x 8)**

- a) Explain stuck-at fault model with examples for s-a-0 and s-a-1 in a logic line.
- b) Explain how interconnect parasitic affect switching delay in VLSI systems.
- c) Explain stick diagrams and draw stick diagram for CMOS inverter.
- d) Write detailed note on CMOS layout design, masks, and  $\lambda$ -based design rules.
- e) Design CMOS logic circuits for following functions:  
(I)  $Y = A+B'$  (II)  $Y = AB + C$
- f) Discuss BIST architecture and its types
- g) Describe working principle and structure of 6T SRAM cell.
- h) A CMOS inverter has load capacitance =  $50 \text{ pF}$  and  $R = 8 \text{ k}\Omega$ . Calculate rise time, fall time, and propagation delay.
- i) Describe the various steps involved in CMOS n-well fabrication process.
- j) Explain Built-In-Self-Test (BIST) architecture with MISR and LFSR block diagram.
- k) Explain operation of 6-T SRAM with neat circuit diagram & timing waveform.

I) Explain stability analysis of SRAM cell using butterfly curves.

### Part-III

#### Only Long Answer Type Questions (Answer Any Two out of Four)

**Q3** (a) Derive the delay time expressions for CMOS inverter and discuss design for minimum delay (10)  
(b) Explain estimation of interconnect delay in MOS circuits with examples (6)

**Q4** (a) Describe dynamic logic circuits in detail with operation, structure and timing issues. (10)  
(b) Discuss high-performance dynamic CMOS circuits. (6)

**Q5** (a) Compare DRAM, SRAM and Flash memory based on structure, speed, power and applications. (10)  
(b) Explain non-volatile memory organization with diagrams. (6)

**Q6** A CMOS inverter drives a load of  $CL = 120 \text{ fF}$ . PMOS width =  $3 \mu\text{m}$ , NMOS width =  $1 \mu\text{m}$ ,  $\mu_p = 150 \text{ cm}^2/\text{V}\cdot\text{s}$ ,  $\mu_n = 450 \text{ cm}^2/\text{V}\cdot\text{s}$  (16)  
(a) Compute propagation delay.  
(b) Estimate dynamic power at 100 MHz,  $VDD=1.8V$ .